

# Spirox Corporation (Stock Code :3055) 2023 Third Quarter Earnings Conference

Spokesperson Noelle Ni 21 Dec 2023

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## Agenda

- Company Profile
- Financial Review
- 2023.4Q & 2024 Outlook
- Q&A





## Spirox Group

Professional Semiconductor Equipment Provider

## **Overview**



#### Hsinchu, Taiwan | HQ



- Own Products
- Semiconductor Equipment Distribution

**Southport Corporation** 

Advanced Optics Technologies

· Board Repair Service

#### **Subsidiary**

#### Jetek Technology Corp.

- · System Integration Services
- Customized Test Solutions

#### Spirox Technology Shanghai

- · Semiconductor Equipment Distribution
- · Board Repair Service

#### **Spirox Group**

- Established in 1987
- TWSE: 3055, Listed in 2002
- Capital: 38.3M USD
- Market Cap: 154M USD (as of 2023/12/13)
- Employees: 180 (as of 2023)
- Business Coverage: Semiconductor Test/Package/Inspection Equipment

#### **Spirox Products**

- SP2500 SoC Test System
- MA6503D Micro Inspection System
- SP3055A Non-destructive Inspection System
- SP3055S WBG Materials Inspection and Analysis System

#### **Distribution Products**















## **Core Competencies**





#### **Business Philosophy**

Build a customer-oriented culture and set win-win goals with customers and partners.



#### **Industry Experience**

With over 30 years of experience in semiconductor industry, Spirox has a strong and stable customer base.



#### **Professional Team**

- Years of service:
  140 employees with 5Y+
  103 employees with 10Y+
  82 employees with 15Y+
  55 employees with 20Y+
- Education:
- 138 employees have a college degree or higher (77%) 40 employees have a master's degree (22%) 2 employees have a PhD (1%)



#### **R&D** Capability

Test solution development and Investment on own-product

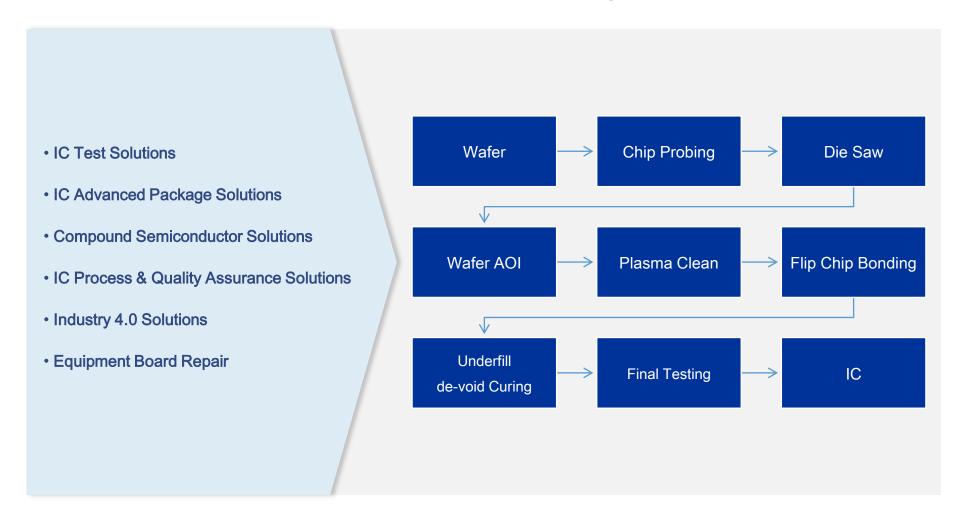


#### **Strong FIN**

Strong & health finance status

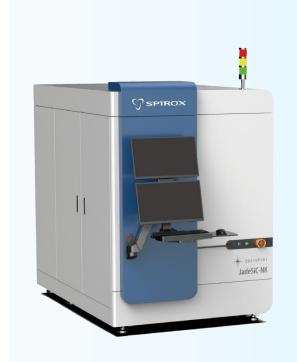


## Spirox solution can meet the demands of the front-end and back-end semiconductor manufacturing processes!





## **Compound Semiconductor Solutions**



#### JadeSiC-NK

#### Non-Destructive Inspection System

- Advanced NLO (non-linear optics) technology
- Non-destructive inspection technology
- Killer defects (BPD, TED, TSD, MicroPipe, SF) inspection on the surface and in the substrate
- MicroArea 3D scan function available

#### JadeSA-WBG

#### 3D Stress Inspection & Analysis System

- Wafer scan on surface and in depth for stress distribution
- Whole wafer scan at specific depth with stress mapping
- Whole wafer 3D polytype analysis
- MicroArea 3D stress mapping / polytype analysis





## Assembly and Test + Quality Assurance Solutions

**Chip Probing** 



IC Package



**IC Final Testing** 

IC Process & Quality Assurance



















ATE

Handler

Prober

Chuck

Test Interface

MicroLED Inspection







@ 和研科技























TCB Bonder

Blade Dicing Saw Vacuum Reflow

Reflow system

De-void system

Plasma

Heat Sink Measurement Laminator

Automatic Debond Warpage Adjustment



**EFA** 



PFA



MA















**ESD** 

AOI(PKG)

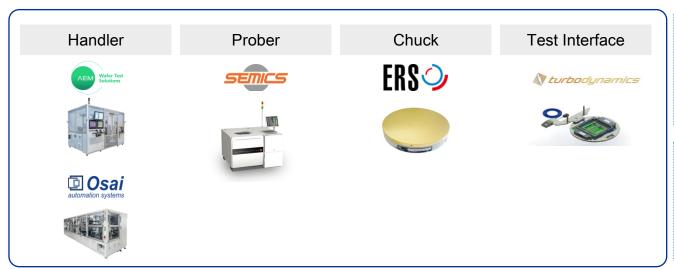
AOI(Wafer)



## **Test Solution**











## **Advanced Package Solutions**



#### **TORAY**

Toray Engineering Co.,Ltd.



Thermal Compression Bonding (TCB)

#### Metrology





Multi function measurement system

#### Material





Bare Si Wafer

#### Automatic





Mobile Robot

#### **Process**

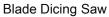














eWLB wafer de-bonding Warpage Adjustment



Vacuum Reflow System



Reflow system





De-void system





Plasma





Heat Sink Laminator



## **Process & Quality Assurance Solutions**

**High Reliability** 



Litho



































#### **EFA**

- Front side/Back side EFA
- Static/Dyanmic EFA
- Magnetic Optical Current Imaging

#### **PFA**

- SEM
- FIB/Plasma FIB
- MicroCT

#### MA

- Nanometer Materials
- SiC/GaN 3D Defect Analysis
- Micro LED Inspection
- Perovskite Inspection

HBM/CDM/TLP ESD

**ESD** 

- Lactch Up
- Wafer Level ESD

#### **Nanoprobes**

 Can meet the demands for failure analysis in 3 nm process



## **Process & Quality Assurance Solutions**

**High Reliability** 























#### AOI (Wafer)

- Whole Wafer/Sawn Wafer
- Thin Wafer
- Color Camera Inspection





#### AOI (Wafer)

- Replace QC visual inspection on surface defects
- Auto-storing Defects Image
- Position Coordinate Records





#### AOI (PKG)

- Package inspection with Auto Tape & Reel / 6S
- High Speed In Tray / Pick & Place Solution





#### AOI (PKG)

- Auto-pitch adjustment of sealing blade for efficient operation
- Post-sealing inspection ensures high quality service
- Friendly user-interface





#### AOI (PKG)

- Replace manual IQC incoming inspection
- Replace manual FT first tray inspection and in-process quality control (IPQC)
- Provide tray maps for data comparison and tracking



## **Customization Test Solutions**



System Integration

Flexibility: Fast function expansion

Friendly: One Human-Computer Interface

Test Module Board Design

Develop cost-effective and precise measure module to fulfill customer demands

Software Development

Customized developing environment and analysis tools for more effective engineering process

Highly Customized

Close team work with customers to achieve win-win goal



**Bio-Sensor** 



CIS



MEMS (MIC,TPMS)



## **Achievements**

For over 30 years, Spirox has contributed to the success of semiconductor industries through cost reduction, improved efficiency, and offering the most advanced range of technology equipment in the field.

Spirox will continue to uphold our commitment to seek out and deliver smarter solutions that provide a competitive advantage for both our customers and partners!

12K+

**Total Installed** 

4K+

**Training Attendance** 

1.7K+

**Customers Served** 

500+

**Vendor Codes** 

Spirox always delivers smarter solutions!



## **Financial Review**

## Statements of Consolidated Income (YoY & QoQ)

SPIROX CORPORATION and Subsidiaries

	Summary of Consolidated Statements of Income (In NT\$ Millions)							
	2022/ Q3	2022/ Q4	2023/ Q1	2023/ Q2	2023/ Q3	2022/ ~Q3	2023/ ~Q3	
Net Revenue	588	396	365	358	312	1,519	1,035	
YoY	(28)	(445)	(80)	(128)	(276)	(287)	(484)	
YoY%	-4.5%	-52.9%	-18.0%	-26.3%	-47.0%	-15.9%	-31.9%	
Gross Profit	47	(1)	25	73	69	173	167	
YoY	(4)	(112)	(38)	11	22	(20)	(5)	$\leftarrow$
YoY%	-8.3%	-100.9%	-60.3%	17.3%	46.5%	-10.5%	-3.2%	$\leftarrow$
GP Margin %	8.0%	-0.3%	6.9%	20.5%	22.1%	11.4%	16.2%	
Operating Expenses	149	156	108	93	121	434	322	
YoY	(40)	21	(36)	(48)	(28)	(92)	(112)	$\leftarrow$
YoY%	-21.1%	15.6%	-25.3%	-34.2%	-18.7%	-17.5%	-25.9%	<del>-</del>
Operating Income (loss)	(102)	(157)	(82)	(19)	(52)	(259)	(154)	
YoY	36	(134)	(2)	57	50	72	105	<b>~</b>
YoY%	-26.1%	-581.5%	-2.0%	74.6%	48.7%	21.6%	40.5%	<b>←</b>
Op. Income(loss) margin%	-17.3%	-39.7%	-22.5%	-5.4%	-16.8%	-17.1%	-14.9%	
Non-Operating Revenue and Expenses	231	540	208	(25)	(74)	193	109	
YoY	222	553	222	(1)	(305)	176	(84)	
YoY%	2484.5%	4077.8%	1627.9%	-3.3%	-132.0%	988.2%	-43.4%	
as % of revenue	39.3%	136.5%	57.0%	-6.9%	-23.7%	12.7%	10.6%	
Net Income (loss)	110	333	103	(49)	(118)	(77)	(63)	
YoY	233	385	199	43	(228)	237	13	<b>←</b>
YoY%	190.1%	751.0%	207.7%	46.7%	-207.2%	75.6%	17.4%	<b>(</b>
Net Income (loss) margin%	18.7%	84.3%	28.2%	-13.6%	-37.8%	-17.7%	-19.7%	
Net Incom (loss) attributable to:								
Owners of the Parent	115	293	103	(49)	(118)	(53)	(63)	
Non-controlling interests	(4)	41	(0)	0	0	(24)	(0)	
EPS (NT Dollars)	1.02	3.88	0.91	(0.43)	(1.03)	(0.47)	(0.55)	

note: The profit and loss of the continued business and the discounted operation are shown separately



## **Consolidated Balance Sheet**

SPIROX CORPORATION and Subsidiaries

Summary of C	Summary of Consolidated Balance Sheet			(In NT\$ Millions)		
	2021.12.31	2022.9.30	2022.12.31	2023.09.30	change	
Cash and time deposits(AC)	1,247	1,321	1,226	1,424	198	
Accounts Receivable,net	873	719	506	325	(181)	
Other receivable, net	8	8	667	87	(580)	
Inventories	172	197	172	49	(123)	
Disposal groups held for sale	1,910	27	0	0	0	
Other current assets	180	131	114	94	(20)	
Financial Assets(except AC)	502	662	698	756	58	
Property, plant and equipment	1,425	1,382	623	599	(23)	
Non-current assets	89	73	42	48	6	
Total Assets	6,407	4,521	4,048	3,383	(665)	
Borrowings	1,134	828	476	290	(187)	
Contract Liabilities	83	103	95	113	18	
Account payable	730	667	486	289	(197)	
Disposal groups held for sale	1,641	0	0	0	0	
Other liabilities	177	134	154	171	17	
Total Liabilities	3,766	1,732	1,211	862	(349)	
Common Stock	1,187	1,187	1,187	1,187	0	
Additional Paid-In Capital	467	832	618	435	(183)	
Retained Earnings	1,099	1,047	1,335	1,155	(180)	
Other Equity+Treasury Stock	(435)	(375)	(360)	(257)	104	
Minority Interest	323	98	57	0	(57)	
Total equity	2,641	2,789	2,837	2,521	(317)	



transferred



## Consolidated Cash Flow Highlights & Financial Ratio

Consolidated Statements of Cash Floows Summary			(In NT\$ Millions)					
item	2021	2022/ ~Q3	2022	2023/ ~Q3				
Net cash generated from (used in) operating activities	(117	308	253	117	$\leftarrow$			
Net cash used in investing activities	(119	) 76	(245)	552	<del>&lt;</del>			
Net cash generated from financing activities	358	(100)	64	(481)				
Cash and cash equivalents at the end of the year	1,042	1,265	1,103	1,327	Adjusting			
held financial structure and debt solvency well Financial Analysis Summary  operating performance								
	2021	2022/	2022	2023/	1			
item	2021	~Q3	2022	~Q3				
Account Receivable turnover days	<b>×</b> 194	<b>√</b> 146	<b>√</b> 135	<b>√</b> 118	←			
Inventory turnover days	<b>4</b> 8	<b>×</b> 74	<b>√</b> 51	<b>×</b> 65				
Debts ratio%	<b>₹</b> 58.78%	<b>₹</b> 38.32%	<b>√</b> 29.91%	<b>√</b> 25.48%	$\leftarrow$			
Current ratio%	<b>√</b> 141.48%	<b>√</b> 197.95%	<b>√</b> 402.91%	<b>√</b> 432.09%	4			
ROA%	-4.64%	·0.27%	5.36%	-1.53%				

■ -14.58%

-2.82%

9.37%



ROE%

-2.36%



## 2023.4Q & 2024 Outlook

## 2023.4Q & 2024 Outlook: Semiconductor Equipment Distribution

- Due to the global downturn in the semiconductor market and the slow pace of inventory digestion, customers are cautious in terms of pulling orders and investments. The booking status is lower than expected. However, influenced by the intensified restrictions on the Chinese semiconductor market by the United States and Japan, some customers accelerated their order placement at the end of the year, leading to the continuous shipment of equipment. The revenue from semiconductor equipment distribution in 2023 is expected to decrease by approximately 16% compared to 2022.
- Rebalance product portfolio and market strategy:

**Distribution:** focus on low US-tech involved products and transfer to buy-and-sell mode to increase gross profit, including

- TESCAN(CZECH): FIB SEM and Microscope
- Wafer Prober (KOREA): for wafer testing
- Hamamatsu (JAPAN): for wafer electrical failure analysis
- Toray TCB(JAPAN): for high-level stacked package



### 2023.4Q & 2024 Outlook: Spirox Own-brand Equipment

- Rebalance product portfolio and market strategy:
  - Spirox Own-brand products: best way to increase gross profit rate
  - 1.Expansion of product portfolio through the acquisition of Southport
    - JadeSiC-NK: Industry-first Non-Destructive SiC Defect Inspection System. It
      employs advanced non-linear optical technology for whole wafer scanning of SiC
      substrates to identifying killer defects within the substrate, and can help
      customers saving significant costs and increasing output. In negotiation with
      several customers.
    - JadeSA-WBG: 3D Stress Inspection and Analysis System for WBG Materials. It can effectively reflect the intrinsic property of WBG materials, and suitable for monitor the stress distribution and polytype uniformity of SiC substrate, homogeneous and heterogeneous epi wafer, and device process review. In negotiation with several customers.

#### 2.Other Own-brand products:

● AOI Equipment: MA6503D、TR1000、LS1000

● ATE: SP2500



#### 2023.4Q & 2024 Outlook: Subsidiaries & Investment

#### Jetek Technology (Taiwan):

 Keep developing CIS and Silicon Photonics solution. Silicon Photonics solutions has shipped in 2<sup>nd</sup> half of 2023, and CIS solution is expected to generate revenue and profit in 2024.

#### Southport Corporation:

- Participated in Southport 's cash capital increase to complete 1st phase investment to obtain about 51% of the equity of Southport (Approximately 3.09million shares)
- 2nd phase investment will be conducted after Southport completes the performance goals set by Spirox. Spirox is expected to obtain a total of 95% of the equity of Southport for two phase investment.

#### • UnionSemicon (Hefei):

- Holding 2.04% shares (17 million shares)
- Trading restrictions was released on 18<sup>th</sup> Dec 2023. Will sell our shares based on market conditions and stock prices.





## Thank You!